MUR460

Ultrafast power diode

Rev.01 - 19 March 2024 Product data sheet

1. General description

Ultrafast power diode in a SMC package

2. Features and benefits

- Fast switching
- SMC package
- High voltage capability
- Low forward voltage drop
- Low leakage current
- Low thermal resistance
- Soft recovery characteristic

3. Applications

- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)
- High frequency switched-mode power supplies

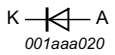
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
Absolute maximum rating							
V_{RRM}	repetitive peak reverse voltage			600			V
$I_{F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; $T_{lead} \leq 102$ °C; Fig. 1; Fig. 2; Fig. 3		4			A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; $T_{lead} \leq 102$ °C; square-wave pulse		8			A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		100			A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		110			A
Symbol	**Parameter**	**Conditions**	**Notes**	**Min**	**Typ**	**Max**	**Unit**
Static characteristics							
V_F	forward voltage	I_F = 4 A; T_j = 25 °C; Fig. 6		-	1.16	1.35	V
		I_F = 4 A; T_j = 150 °C; Fig. 6		-	0.93	1.25	V
Dynamic characteristics							
t_{rr}	reverse recovery time	I_F = 1 A; V_R = 30 V; dI_F/dt = 50 A/µs; T_j = 25 °C; Fig. 7		-	40	-	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		

6. Ordering information

Table 3. Ordering information

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
MUR460	SMC	MUR460,118	Reel	3000	SMCS	16-Aug-2017

7. Marking

Table 4. Marking codes

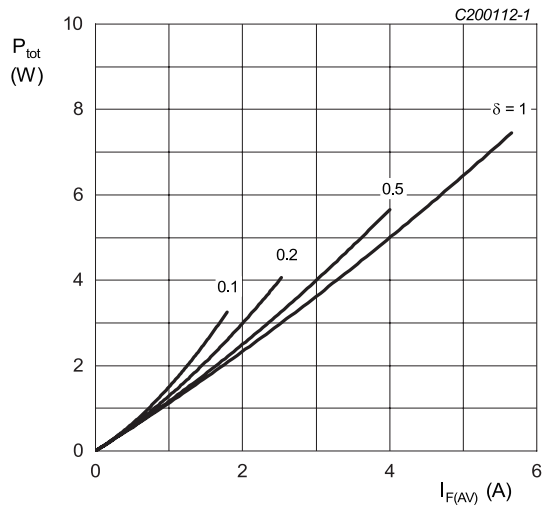
Type number	Marking codes
MUR460	460JE

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

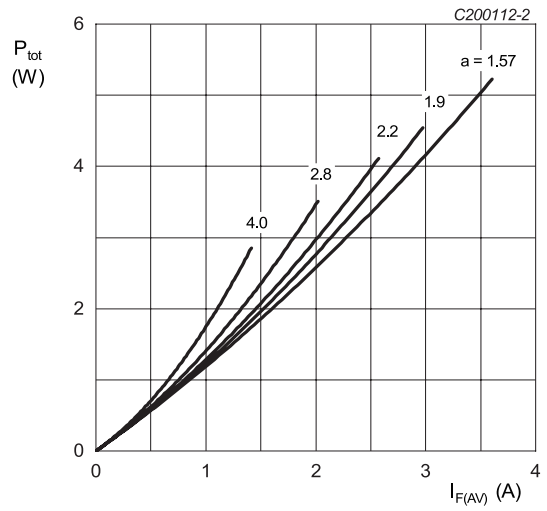
Symbol	Parameter	Conditions	Notes	Values	Unit
V_{RRM}	repetitive peak reverse voltage			600	V
V_{RWM}	crest working reverse voltage			600	V
V_R	reverse voltage	DC		600	V
$I_{F(AV)}$	average forward current	δ = 0.5 ; square-wave pulse; $T_{lead} \leq 102$ °C; Fig. 1; Fig. 2; Fig. 3		4	A
I_{FRM}	repetitive peak forward current	δ = 0.5 ; t_p = 25 µs; $T_{lead} \leq 102$ °C; square-wave pulse		8	A
I_{FSM}	non-repetitive peak forward current	t_p = 10 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse; Fig. 4		100	A
		t_p = 8.3 ms; $T_{j(init)}$ = 25 °C; sine-wave pulse		110	A
T_{stg}	storage temperature			-65 to 175	°C
T_j	junction temperature			-65 to 175	°C



$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$

V_o = 1.083 V; R_s = 0.0413 Ω

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



a = form factor = $I_{F(RMS)} / I_{F(AV)}$

V_o = 1.083 V; R_s = 0.0413 Ω

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

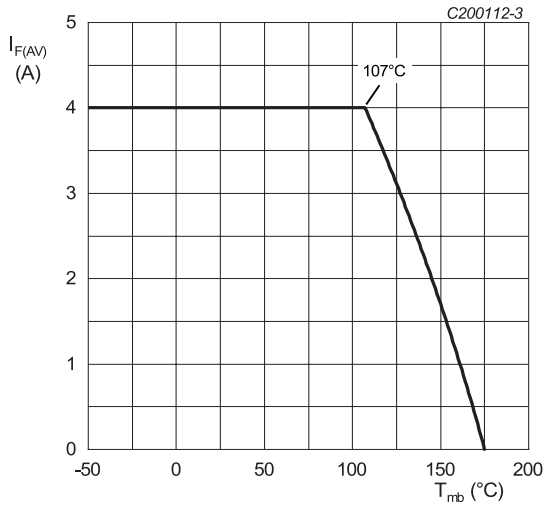


Fig. 3. Forward current as a function of lead temperature; maximum values

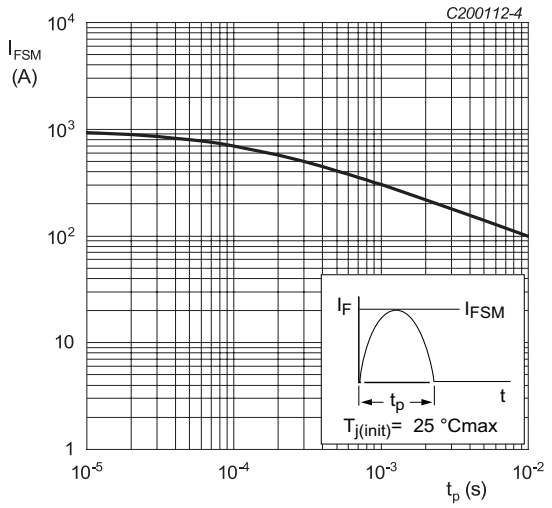


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j\text{-}lead)}$	thermal resistance from junction to lead	Fig. 5		-	-	12	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient free air	in free air		-	75	-	K/W

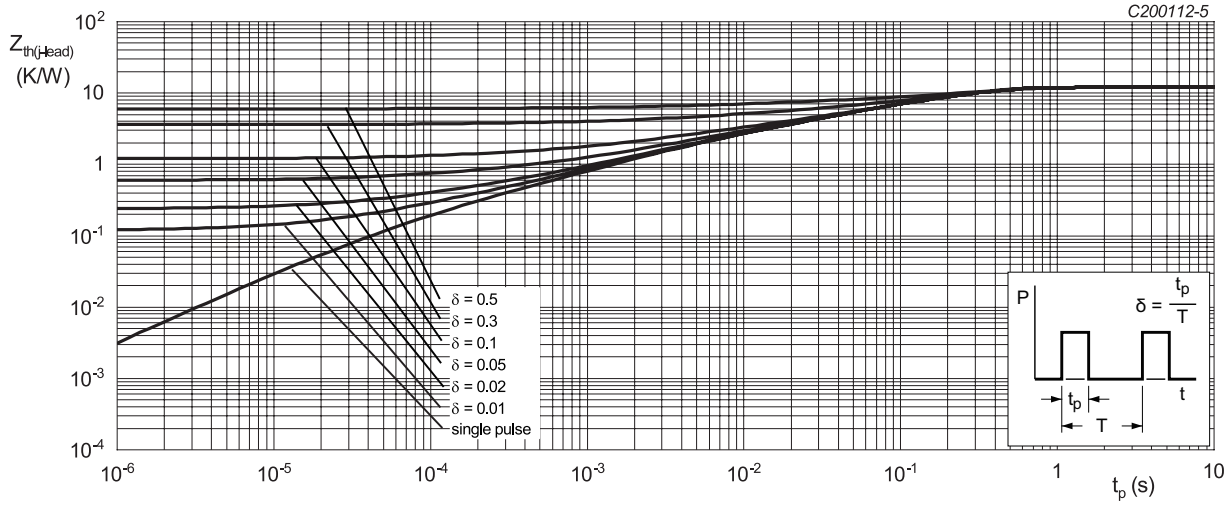
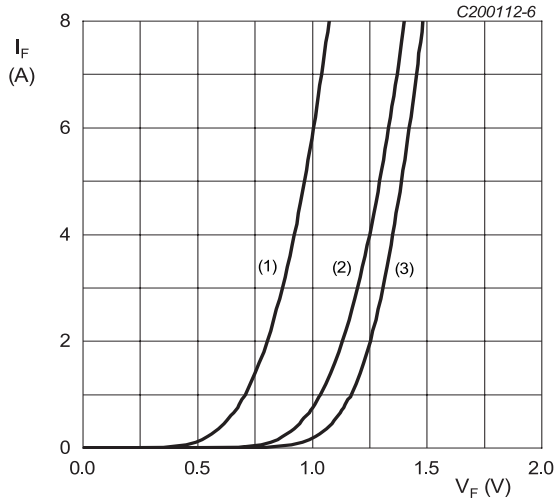


Fig. 5. Transient thermal impedance from junction to lead as a function of pulse duration; maximum values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
V_F	forward voltage	I_F = 4 A; T_j = 25 °C; Fig. 6		-	1.16	1.35	V
		I_F = 4 A; T_j = 150 °C; Fig. 6		-	0.93	1.25	V
I_R	reverse current	V_R = 600 V; T_j = 25 °C		-	-	3	µA
		V_R = 600 V; T_j = 150 °C		-	-	1	mA
Dynamic characteristics							
Q_r	reverse charge	I_F = 4 A; V_R = 400 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	119	-	nC
		I_F = 4 A; V_R = 400 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	222	-	nC
t_{rr}	reverse recovery time	I_F = 0.5 A; I_{RR} = 0.25 A; I_R = 1 A; T_j = 25 °C		-	-	50	ns
		I_F = 1 A; V_R = 30 V; dI_F/dt = 50 A/µs; T_j = 25 °C; Fig. 7		-	40	-	ns
		I_F = 4 A; V_R = 400 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	49	-	ns
		I_F = 4 A; V_R = 400 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	67	-	ns
I_{RM}	peak reverse recovery current	I_F = 4 A; V_R = 400 V; dI_F/dt = 200 A/µs; T_j = 25 °C; Fig. 7		-	4.8	-	A
		I_F = 4 A; V_R = 400 V; dI_F/dt = 200 A/µs; T_j = 125 °C; Fig. 7		-	6.5	-	A
E_{as}	non-repetitive avalanche energy	$T_{j(init)}$ = 25 °C		10.8	-	-	mJ



V_o = 1.083 V; R_s = 0.0413 Ω
(1) T_j = 150 °C; typical values
(2) T_j = 150 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 6. Forward current as a function of forward voltage

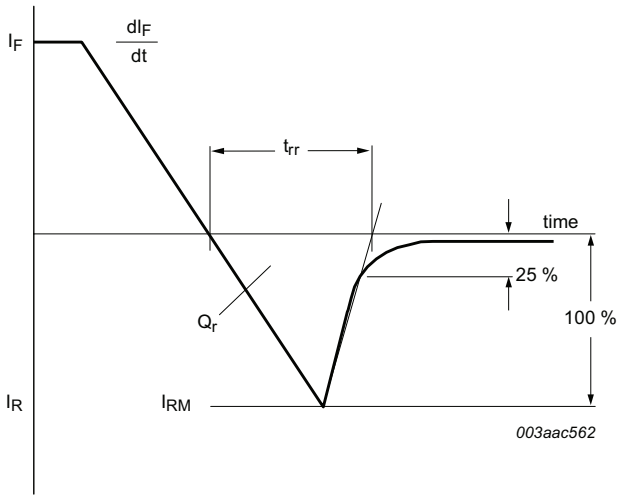
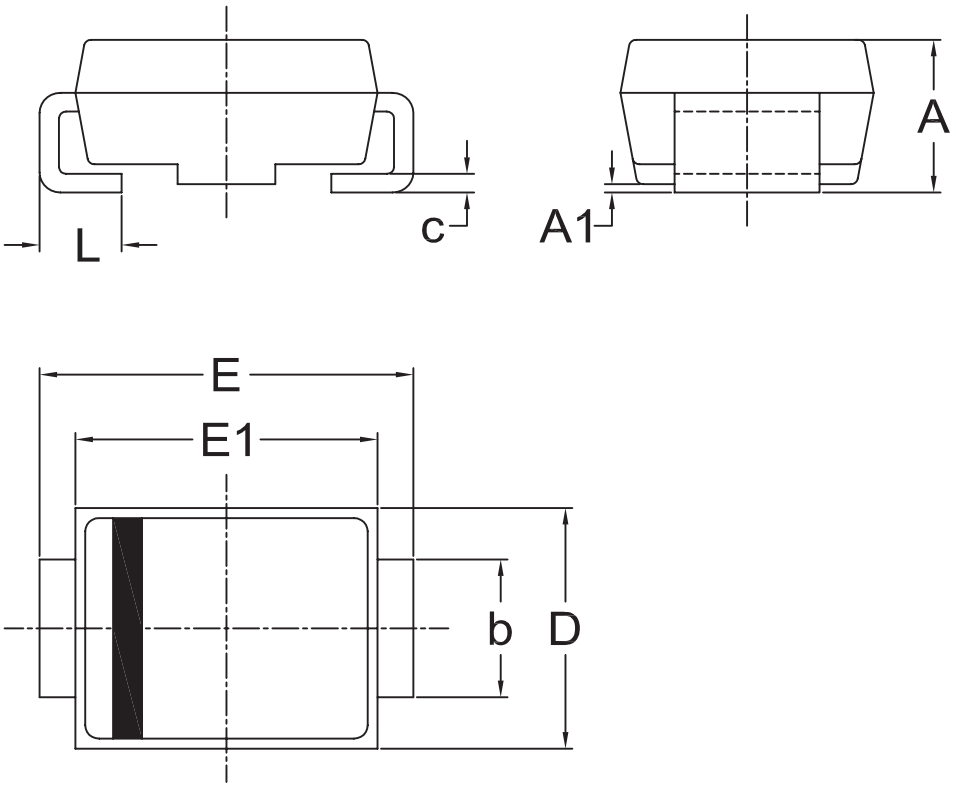


Fig. 7. Reverse recovery definitions; ramp recovery

11. Package outline



UNIT		A	A1	b	c	D	E	E1	L
mm	Max	2.40	0.22	3.18	0.31	6.22	8.13	7.11	1.52
	Min	2.01	0.05	2.92	0.15	5.59	7.70	6.60	0.76

Remark: Dimensions D and E1 do not include mold flash.

12. Legal information

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Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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[2] The term 'short data sheet' is explained in section "Definitions".
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13. Contents

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